1. The board I/o consists of 5 N/W connectors and the bus connector.

2. The ground integrity is critical for some parts of the assembly system. Minimal cross-over bypass grounds and minimal breaks in main ground planes.

3. Inductors should be perpendicular to each other if close together.

4. A 4 layer board is suggested. Soldermask thicknesses of 0.010", 0.020", and 0.016" respectively.

5. 0.050" power and ground lines where possible 0.032" main signal line where possible (printed by M).

6. The high digital components (U31-254, U24, and associated bypass caps) must be near the bus.

7. The LED output drive (p. 8) must be in Box A.

8. 2 standard selection board sizes should be used. The 5 MWCs and TRs on one circuit board. No on other.

9. TR ADICOMPUTER 1-8/78. P/A 19.0221 11.000 CD
   i2: TR OUT T/R 10: NO OUT

10. The base of Q19 should have at least 3 gnd via immediately near the pin.

11. The layout of the first NF amplifier (Q1-Q2,...) is particularly critical. Leads must be very short and decoupling capacitance maximized.

REV 1.0 - INITIAL PCB; REV 1

REV 2.0 - REV A PCB RELAISE TO PELLO/PINE -7E

REV 2.1 - REV SHIELD SIDE 'A' TO SHIELD 'B' JL 1/99

REV 2.2 - REV B MID9973 JL 1/31/98

ADDED CAPS C417, C416 PG 2 ADDED RESISTORS R401, R406 PG 4

REV 3.0 - REV C M378 JL 12/31/98

ADDED RES. R465, R451, R431, R432, R424 PG 4

REV 4.0, May 1997, APP MD CAP 4112, REV. 7/09, L24 PG 4

REV 5.0 Z BOX VALUE PAGE 4, R303 VALUE 7036 5, R314 VALUE 7056 4

REV 6.1 - REV C M374 JL 12/24/98 REV. A72 PAGE 6

REV 7.1 - REV D M374 JL 1/7/97 ADDED CR3. CR4 PAGE 6

REV 7.2 - REV F M374 JL 1/14/99 REV. 144 PAGE 6

REV 7.3 - REV E M374 JL 1/16/99 REV. 144 VALUE.


